

2A, 20V - 150V Schottky Barrier Surface Mount Rectifier

FEATURES

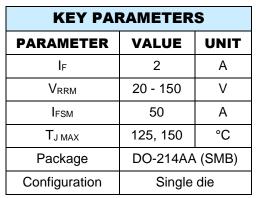
- Low power loss, high efficiency
- Ideal for automated placement
- Guard ring for over-voltage protection
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.093g (approximately)











DO-214AA (SMB)



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)										
PARAMETER	SYMBOL	SS 22	SS 23	SS 24	SS 25	SS 26	SS 29	SS 210	SS 215	UNIT
Marking code on the device		SS 22	SS 23	SS 24	SS 25	SS 26	SS 29	SS 210	SS 215	
Repetitive peak reverse voltage	V _{RRM}	20	30	40	50	60	90	100	150	V
Reverse voltage, total rms value	V _{R(RMS)}	14	21	28	35	42	63	70	105	V
Forward current	l _F	2					Α			
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	50					А			
Critical rate of rise of off-state voltage	dV/dt	10,000					V/µs			
Junction temperature	TJ	- 55 to +125 - 55 to +150				°C				
Storage temperature	T _{STG}	- 55 to +150					°C			

1

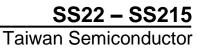


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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	TYP	UNIT			
Junction-to-lead thermal resistance	Rejl	24	°C/W			
Junction-to-ambient thermal resistance	Reja	70	°C/W			

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	SS22		VF			
	SS23			-	0.50	V
	SS24	I _F = 2A, T _J = 25°C				
	SS25 SS26			-	0.70	V
	SS29				0.05	.,,
	SS210			-	0.85	V
	SS215			-	0.95	V
	SS22		VF			
	SS23			-	0.40	V
	SS24			1	_	
5	SS25	I _F = 2A, T _J = 100°C			0.65	V
Forward voltage ⁽¹⁾	SS26			-	0.65	V
	SS29			-	0.70	V
	SS210				0.70	
	SS215			-	0.80	V
	SS22	T _J = 25°C	IR			
	SS23					
	SS24			-	400	μΑ
Develope assument @ retad V (2)	SS25					
Reverse current @ rated V _R ⁽²⁾	SS26					
	SS29			-	100	
	SS210					μΑ
	SS215					
	SS22	T _J = 100°C	l _R			
	SS23			-	10	mA
	SS24					
	SS25				5	mΛ
Reverse current @ rated V _R ⁽²⁾	SS26			<u>-</u>	<u></u>	mA
	SS29					
	SS210			-	-	mA
	SS215					

2





ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Reverse current @ rated V _R ⁽²⁾	SS22					
	SS23	T _J = 125°C		-	-	mA
	SS24					
	SS25			_	_	mA
	SS26		I _R	_	_	IIIA
	SS29					
	SS210			-	5	mA
	SS215					

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION						
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING				
SS2x	DO-214AA (SMB)	3,000 / Tape & Reel				

Notes:

1. "x" defines voltage from 20V(SS22) to 150V(SS215)



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

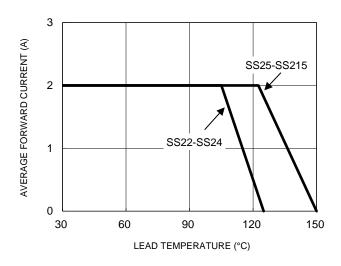


Fig.2 Typical Junction Capacitance

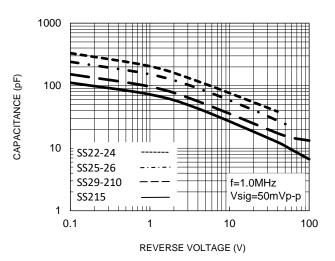


Fig.3 Typical Reverse Characteristics

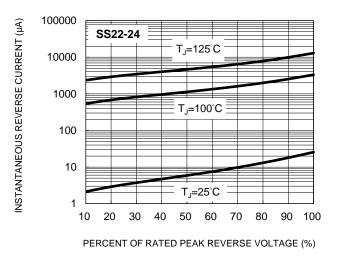


Fig.4 Typical Forward Characteristics

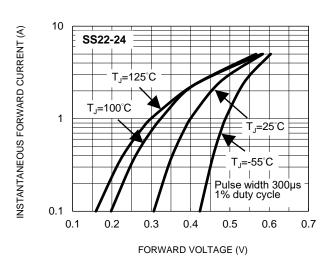


Fig.5 Typical Reverse Characteristics

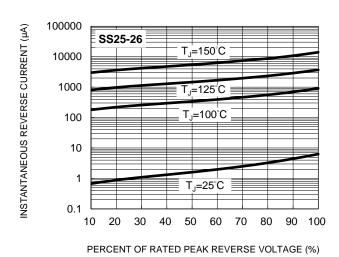
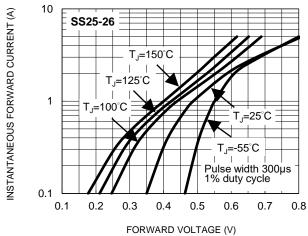


Fig.6 Typical Forward Characteristics





CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.7 Typical Reverse Characteristics

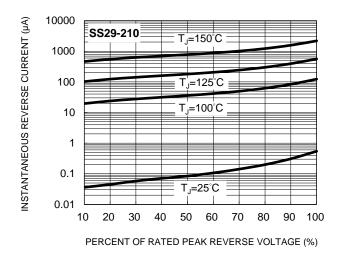


Fig.9 Typical Reverse Characteristics

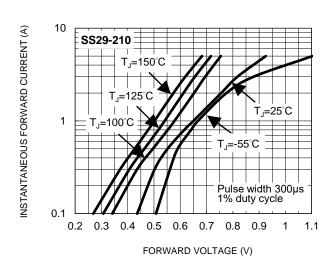
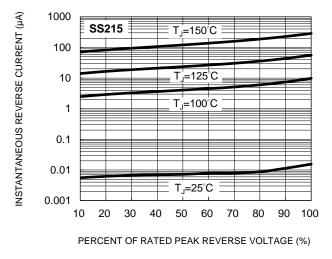


Fig.8 Typical Forward Characteristics

Fig.10 Typical Forward Characteristics



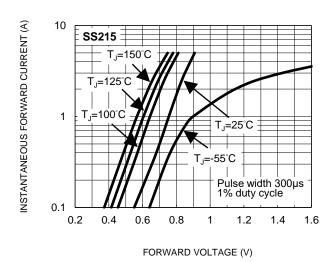
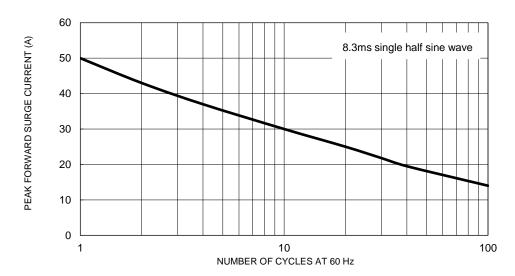


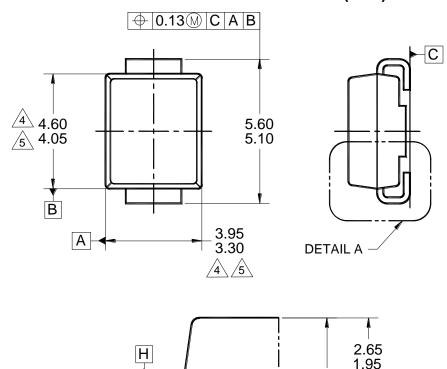
Fig.11 Maximum Non-Repetitive Forward Surge Current

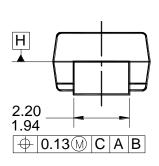


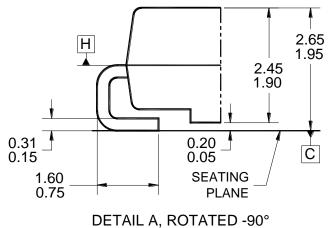


PACKAGE OUTLINE DIMENSIONS

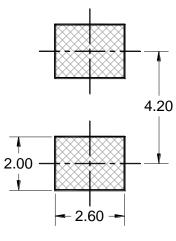
DO-214AA (SMB)



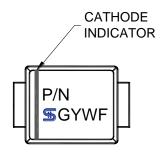




(SCALE 2:1)



SUGGESTED PAD LAYOUT



MARKING DIAGRAM

P/N = MARKING CODE

G = GREEN COMPOUND

YW = DATE CODE

F = FACTORY CODE

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC DO-214, VARIATION AA, ISSUE D.
- MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
- MOLDED PLASTIC BODY LATERAL DIMENSIONS
 TO BE DETERMINED AT DATUM PLANE H.
- 6. DWG NO. REF: HQ2SD07-DO214SMB-035 REV A.



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